



FF1924 - Sn/Pb SOLDER BALLS  
FFG1924 - Sn/Ag/Cu SOLDER BALLS

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	3.20	$\approx$	3.85	
A <sub>1</sub>	0.40	0.50	0.60	
A <sub>2</sub>	1.10	$\approx$	1.50	
D/E	45.00 BASIC			
D <sub>1</sub> /E <sub>1</sub>	43.00 REF			
e	1.00 BASIC			
phi_b	0.50	0.60	0.70	
aaa	$\approx$	$\approx$	0.20	
bbb	$\approx$	$\approx$	0.25	
ddd	$\approx$	$\approx$	0.25	
eee	$\approx$	$\approx$	0.10	
M	44			2

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
2. SYMBOL "M" IS THE PIN MATRIX SIZE.

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## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
11/20/09	1.0	Initial Xilinx release.

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